

# SN54ABT162245, SN74ABT162245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS239F – MARCH 1993 – REVISED JUNE 2004

- Members of the Texas Instruments Widebus™ Family
- A-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- Typical  $V_{OLP}$  (Output Ground Bounce)  $<1$  V at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$
- Distributed  $V_{CC}$  and GND Pins Minimize High-Speed Switching Noise
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

## description/ordering information

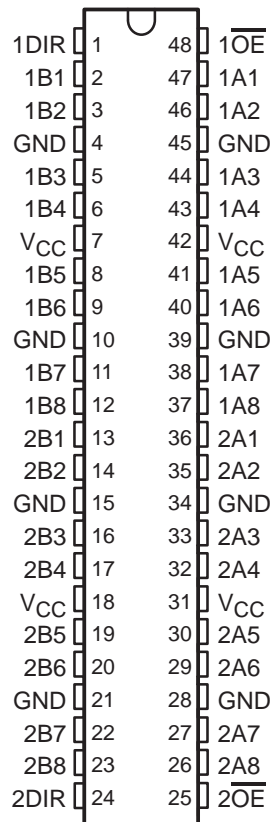
The 'ABT162245 devices are 16-bit noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so that the buses effectively are isolated.

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

SN54ABT162245 . . . WD PACKAGE  
SN74ABT162245 . . . DGG OR DL PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74ABT162245DL	ABT162245
		Tape and reel	SN74ABT162245DLR	
	TSSOP – DGG	Tape and reel	SN74ABT162245DGGR	ABT162245
–55°C to 125°C	CFP – WD	Tube	SNJ54ABT162245WD	SNJ54ABT162245WD

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

**SN54ABT162245, SN74ABT162245**  
**16-BIT BUS TRANSCEIVERS**  
**WITH 3-STATE OUTPUTS**

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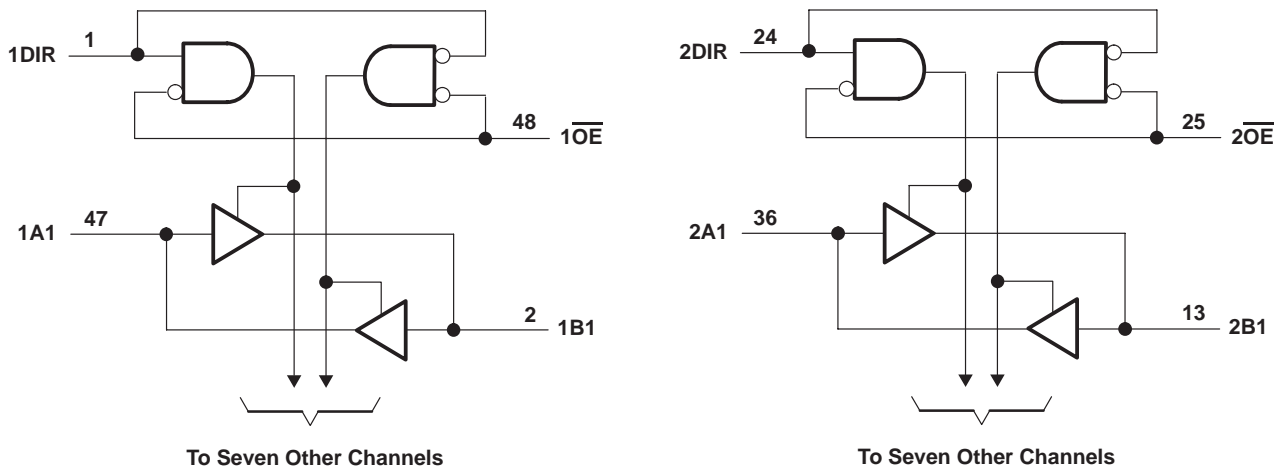
**description/ordering information (continued)**

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

**FUNCTION TABLE**  
(each 8-bit section)

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input voltage range, $V_I$ (except I/O ports) (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, $V_O$	-0.5 V to 5.5 V
Current into any output in the low state, $I_O$ : SN54ABT162245 (B port)	96 mA
SN74ABT162245 (B port)	128 mA
SN54/74ABT162245 (A port)	30 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	-18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	-50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DGG package	70°C/W
DL package	63°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

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**recommended operating conditions (see Note 3)**

		SN54ABT162245		SN74ABT162245		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.5	4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	2		2		V
V <sub>IL</sub>	Low-level input voltage		0.8		0.8	V
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	B port		-24		mA
		A port		-3		
I <sub>OL</sub>	Low-level output current	B port		48		mA
		A port		12		
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10		ns/V
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN54ABT162245, SN74ABT162245

## 16-BIT BUS TRANSCEIVERS

### WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T <sub>A</sub> = 25°C			SN54ABT162245		SN74ABT162245		UNIT		
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX			
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = -18 mA		-1.2			-1.2		-1.2		V		
V <sub>OH</sub>	A port	V <sub>CC</sub> = 5 V, I <sub>OH</sub> = -1 mA	3.8			2.5		2.5		V		
		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -1 mA	3.3			3		3			
			I <sub>OH</sub> = -3 mA	3.1			3		3.1			
	B port	V <sub>CC</sub> = 5 V	I <sub>OH</sub> = -12 mA	2.6*					2.6			
			I <sub>OH</sub> = -3 mA	3			3		3			
		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -3 mA	2.5			2.5		2.5			
V <sub>OL</sub>	A port	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 12 mA	0.8			0.8		0.8		V	
			B port	I <sub>OL</sub> = 48 mA	0.45			0.45		0.45		
				I <sub>OL</sub> = 64 mA	0.55*					0.55		
V <sub>hys</sub>			100							mV		
I <sub>I</sub>	Control inputs	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or GND	±1			±1		±1		μA		
	A or B ports		±20			±20		±20				
I <sub>OZH</sub> §	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.7 V		10			10		10		μA		
I <sub>OZL</sub> §	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0.5 V		-10			-10		-10		μA		
I <sub>off</sub>	V <sub>CC</sub> = 0, V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V		±100					±100		μA		
I <sub>CEX</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V		Outputs high		50			50		μA		
I <sub>O</sub> ¶	A port	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.5 V	-25	-50	-100‡	-25	-90	-25	-100	mA		
	B port		-50	-100	-180	-50	-180	-50	-180			
I <sub>CC</sub>	A or B ports	V <sub>CC</sub> = 5.5 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND	Outputs high		2			2		mA		
			Outputs low		32			32				
			Outputs disabled		2			2				
ΔI <sub>CC</sub> #	Data inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	Outputs enabled		1			2		mA		
			Outputs disabled		0.05			1				
	Control inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	1.5			1.5		1.5				
C <sub>i</sub>	V <sub>I</sub> = 2.5 V or 0.5 V		3							pF		
C <sub>io</sub>	V <sub>O</sub> = 2.5 V or 0.5 V		6							pF		

\* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V<sub>CC</sub> = 5 V.

‡ This limit applies only to the SN74ABT162245.

§ The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

# This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V<sub>CC</sub> or GND.



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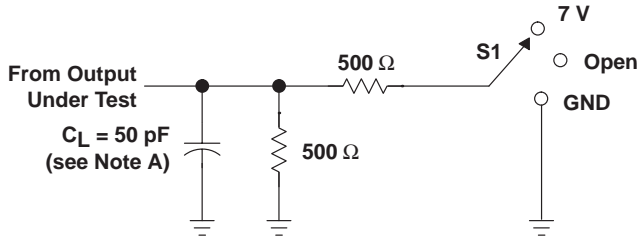
switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ$ C			SN54ABT162245		SN74ABT162245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	B	1	2.2	3.4	1	4.1	1	3.9	ns
$t_{PHL}$			1	2.3	3.7	1	4.4	1	4.2	
$t_{PLH}$	B	A	1	2.7	4.1	1	4.9	1	4.6	ns
$t_{PHL}$			1.5	3.1	4.6	1.5	5.2	1.5	5.1	
$t_{PZH}$	$\overline{OE}$	B	1	3.6	5.2	1	6.4	1	6.3	ns
$t_{PZL}$			1	3.7	5.4	1	6.5	1	6.4	
$t_{PHZ}$	$\overline{OE}$	B	2	4.4	5.8	2	6.4	2	6.3	ns
$t_{PLZ}$			1.5	3.3	4.7	1.5	5.6	1.5	5.2	
$t_{PZH}$	$\overline{OE}$	A	1.5	4.1	6	1.5	7.2	1.5	7.1	ns
$t_{PZL}$			1.5	4.3	6.1	1.5	7.3	1.5	7	
$t_{PHZ}$	$\overline{OE}$	A	2	4.5	6.1	2	6.8	2	6.6	ns
$t_{PLZ}$			1.5	3.7	5.1	1.5	6.1	1.5	5.7	

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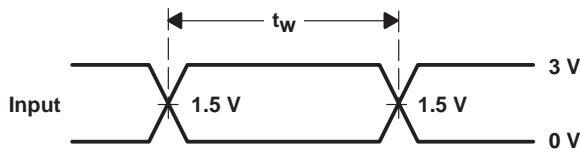
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**PARAMETER MEASUREMENT INFORMATION**

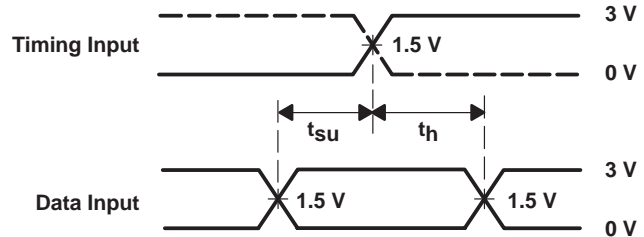


**LOAD CIRCUIT**

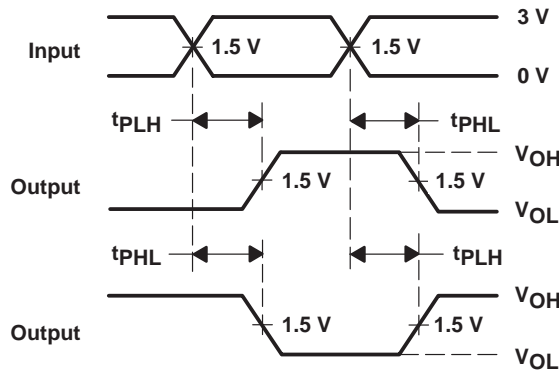
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



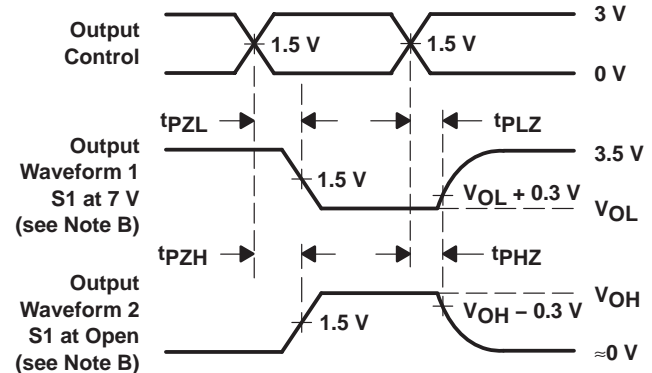
**VOLTAGE WAVEFORMS**  
**PULSE DURATION**



**VOLTAGE WAVEFORMS**  
**SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS**  
**PROPAGATION DELAY TIMES**  
**INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS**  
**ENABLE AND DISABLE TIMES**  
**LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
5962-9677401QXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	Call TI	-55 to 125	5962-9677401QX A SNJ54ABT162245 WD	<a href="#">Samples</a>
74ABT162245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	<a href="#">Samples</a>
74ABT162245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	<a href="#">Samples</a>
74ABT162245DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	<a href="#">Samples</a>
SN74ABT162245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	<a href="#">Samples</a>
SN74ABT162245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	<a href="#">Samples</a>
SN74ABT162245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	<a href="#">Samples</a>
SN74ABT162245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	<a href="#">Samples</a>
SNJ54ABT162245WD	ACTIVE	CFP	WD	48	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9677401QX A SNJ54ABT162245 WD	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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**OTHER QUALIFIED VERSIONS OF SN54ABT162245, SN74ABT162245 :**

- Catalog: [SN74ABT162245](#)
- Military: [SN54ABT162245](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications



## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT162245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ABT162245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



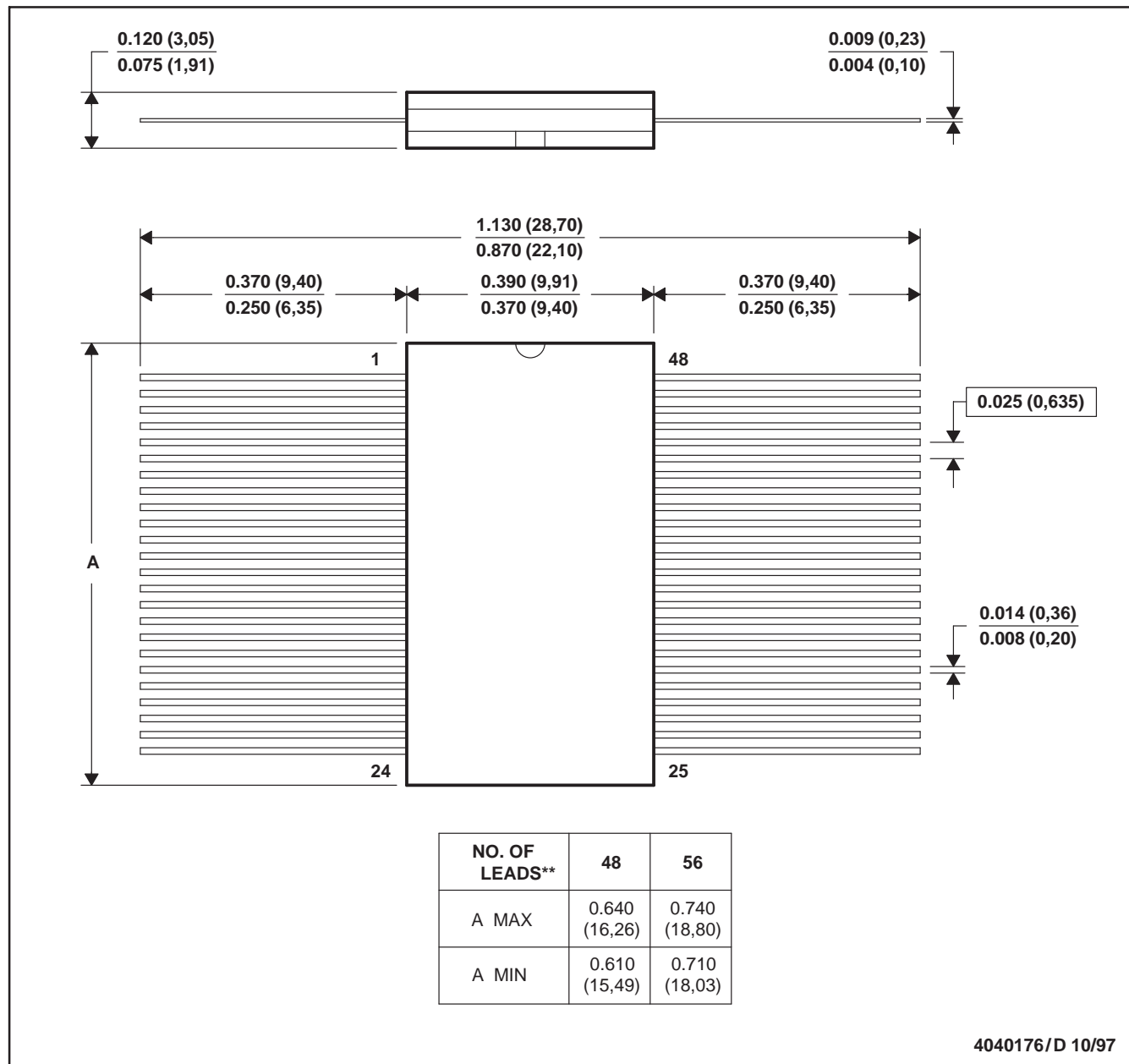
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT162245DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ABT162245DLR	SSOP	DL	48	1000	367.0	367.0	55.0

WD (R-GDFP-F\*\*)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN

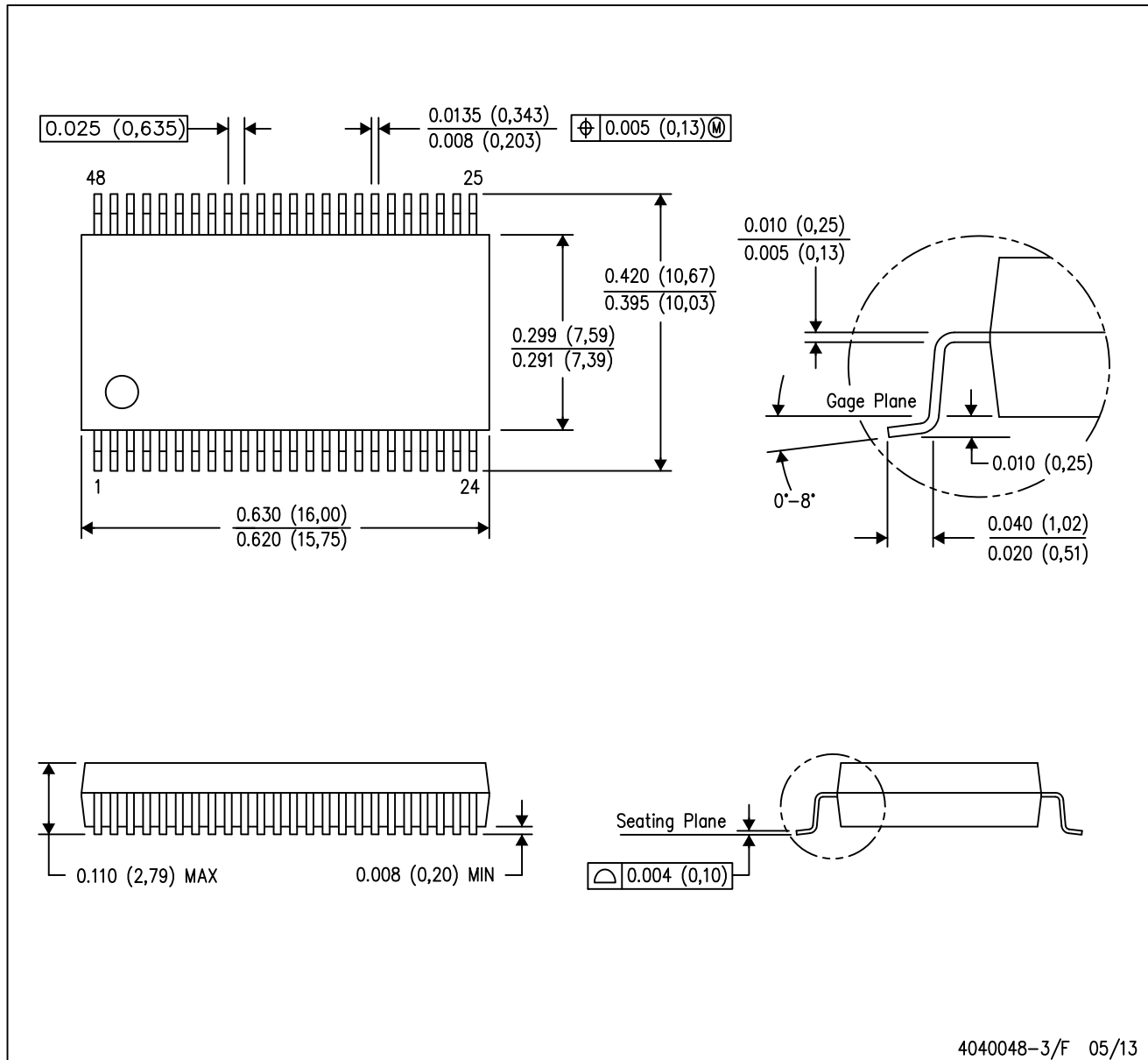


- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only  
 E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA  
 GDFP1-F56 and JEDEC MO-146AB

# MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MO-118

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DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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